TTR5MF

Voltage Range - 1000 Volts Current - 5.0 Ampere

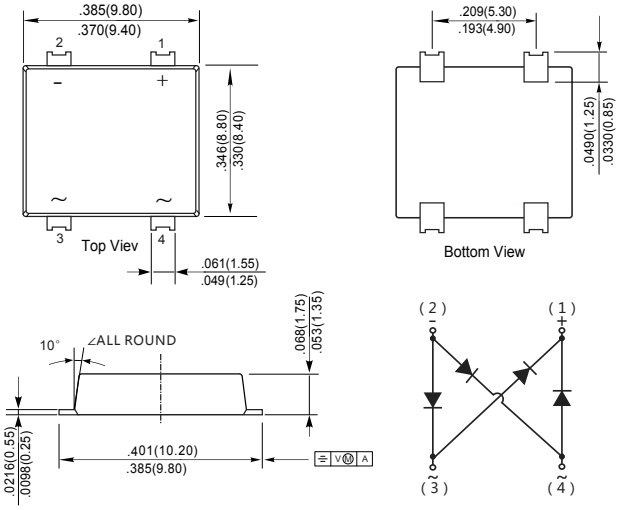
GLASS PASSIVATED SURFACE MOUNT BRIDGE RECTIFIERS

Features

- Glass Passivated Chip Junction
- Reverse Voltage - 1000 V
- Forward Current- 5.0 A
- Fast reverse recovery time
- Designed for Surface Mount Application

TTF

RoHS COMPLIANT



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC TTF molded plastic body
Terminals : Solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body Mounting Position : Any
Weight : 0.0163 ounce, 0.461 grams

Maximum Ratings And Electrical Characteristics (TA=25°C unless otherwise specified)

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load currrent derate by 20% .

PARAMETER	SYMBOL	TTR5MF	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at T_C = 100°C	I_O	5.0	A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	180	A
I^2t Rating for Fusing	I^2t	134.46	A^2S
Typical Thermal Resistance (1)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 6 14	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Maximum Ratings And Electrical Characteristics (TA=25°C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	Units
Instantaneous forward voltage	V_F	I_F =5 A T_J=25℃	–	–	1.1	V
Reverse current at DC blocking voltage	I_R	T_J=25℃ T_J=125℃	– –	– –	5 200	uA
Maximum Reverse Recovery Time	t_{rr}	Measured with I_F = 0.5 A, I_R = 1 A, I = 0.25 A .	–	–	500	ns
Typical Junction Capacitance	C_j	f=1MHz,VR=4V DC T_J=25℃	–	60	–	pF

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4×1.5"×1.5" (3.81×3.81 cm) copper pad areas.

Typical Characterisitics

Fig.1 Average Rectified Output Current Derating Curve

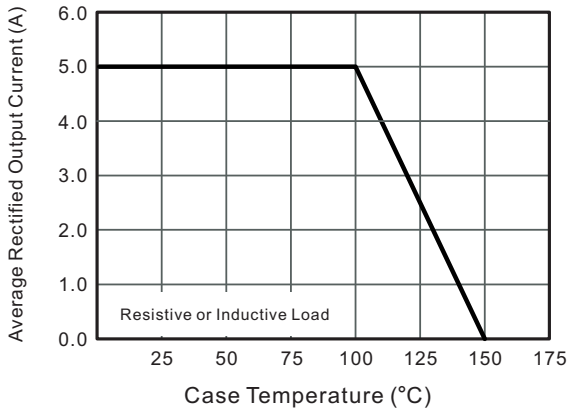


Fig.2 Typical Reverse Characteristics

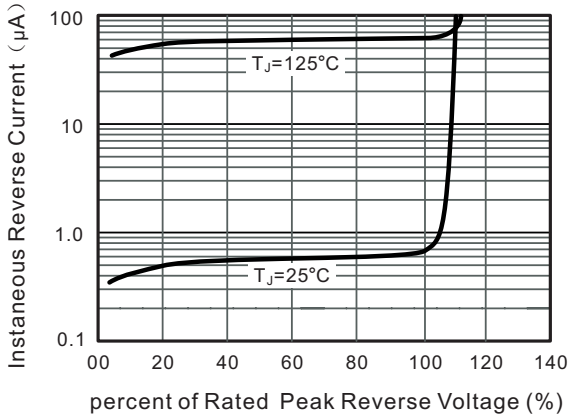


Fig.3 Typical Instaneous Forward Characteristics

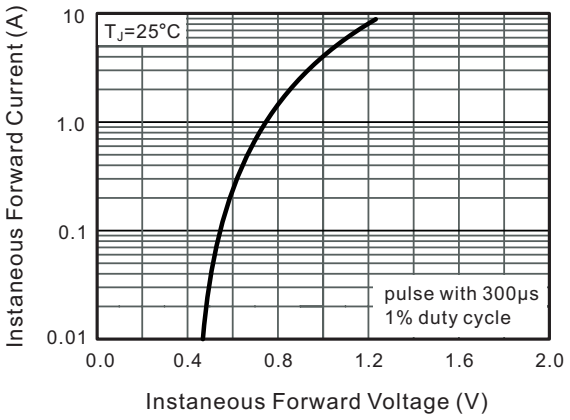


Fig.4 Typical Junction Capacitance

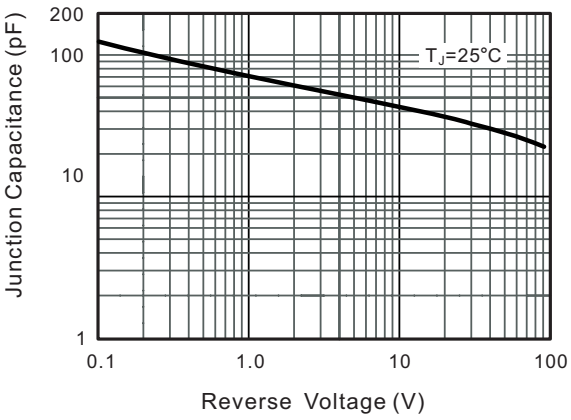


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

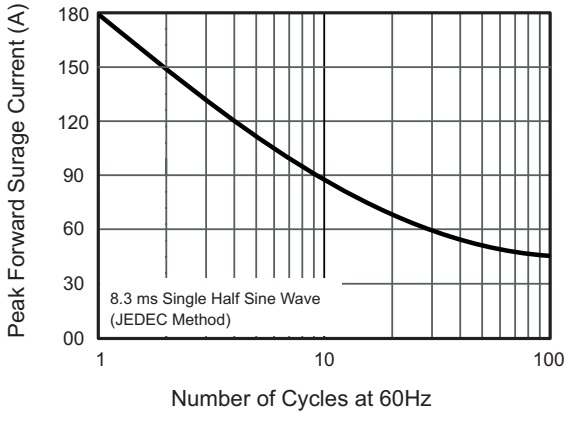
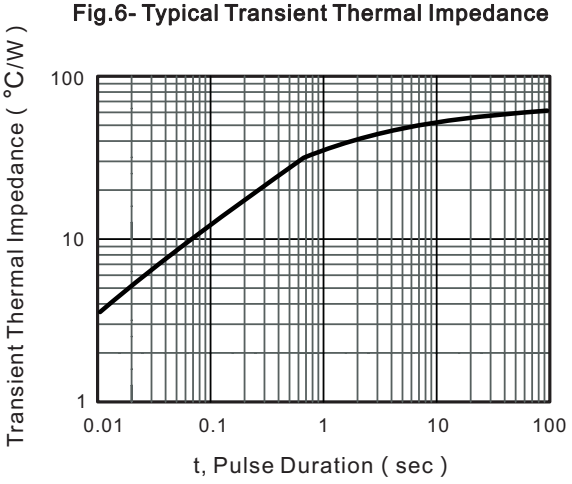
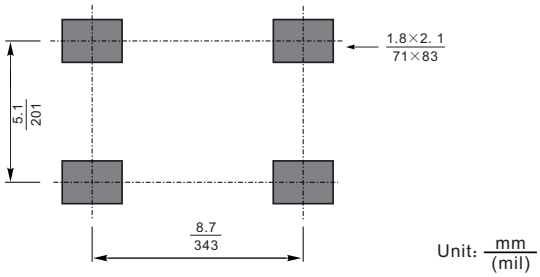


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Suggested Pad Layout



Note:
1.Controlling dimension:in/millimeters.
2.General tolerance: ±0.05mm.
3.The pad layout is for reference purposes only.